



Product Change Notification: DSNO-22KOEN225

Date:

26-Jul-2026

Product Category:

16-Bit Microcontrollers, 32-Bit Microcontrollers, 8-Bit Microcontrollers, Digital Signal Controllers

Notification Subject:

CCB 7116.002 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected DSPIC33EP64GS808xx, DSPIC33EP128GS808xx, DSPIC33EP128GS708xx, DSPIC33EP64GS708xx, PIC24FJ64GA308xx, PIC24FJ128GA308xx, PIC24FJ128GA306xx, PIC24FJ64GA306xx, PIC18F87J94xx, PIC18F85J94xx, PIC18F86J94xx, PIC18F66J94xx, PIC18F65J94xx, PIC18F67J94xx, PIC24FJ128GB204xx, PIC24FJ64GB204xx, PIC24FJ128GA204xx, PIC24FJ64GA204xx, PIC24FJ128GA406xx, PIC24FJ256GA406xx, PIC24FJ64GB406xx, PIC24FJ128GB406xx, PIC24FJ256GB406xx, PIC24FJ64GA406xx, PIC32MX274F256Dxx, PIC32MX154F128Dxx, PIC32MX174F256Dxx, PIC32MX254F128Dxx, PIC24FJ128GC006xx and PIC24FJ64GC006xx device families available in 44L and 64L TQFP (10x10x1mm) and 80L TQFP (12x12x1mm) packages at MTAI assembly site.

Affected CPNs:

[DSNO-22KOEN225_Affected_CPN_07262026.pdf](#)

[DSNO-22KOEN225_Affected_CPN_07262026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected DSPIC33EP64GS808xx, DSPIC33EP128GS808xx, DSPIC33EP128GS708xx, DSPIC33EP64GS708xx, PIC24FJ64GA308xx, PIC24FJ128GA308xx, PIC24FJ128GA306xx, PIC24FJ64GA306xx, PIC18F87J94xx, PIC18F85J94xx, PIC18F86J94xx, PIC18F66J94xx, PIC18F65J94xx, PIC18F67J94xx, PIC24FJ128GB204xx, PIC24FJ64GB204xx, PIC24FJ128GA204xx, PIC24FJ64GA204xx, PIC24FJ128GA406xx, PIC24FJ256GA406xx, PIC24FJ64GB406xx, PIC24FJ128GB406xx, PIC24FJ256GB406xx, PIC24FJ64GA406xx, PIC32MX274F256Dxx, PIC32MX154F128Dxx, PIC32MX174F256Dxx, PIC32MX254F128Dxx,

PIC24FJ128GC006xx and PIC24FJ64GC006xx device families available in 44L and 64L TQFP (10x10x1mm) and 80L TQFP (12x12x1mm) packages at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS-free)	QMI519 (PFAS-free)	No
Molding Compound Material	G700HA	G700HA	No
Lead-Frame Material	C7025	C7025	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material at MTAI assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 07 October 2026 (date code: 2641)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	July 2026					>	October 2026				
Work Week	27	28	29	30	31		40	41	42	43	44
Qual Report Availability				x							
Final PCN Issue Date				x							
Estimated Implementation Date								x			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB# 7116.

Revision History: July 26, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_DSNO-22KOEN225_Qualification Report_CCB7116.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

PIC24FJ64GC006T-I/PT
DSPIC33EP64GS808-I/PT
DSPIC33EP128GS808-I/PT
DSPIC33EP128GS708-I/PT
DSPIC33EP64GS708-E/PT
DSPIC33EP64GS808-E/PT
DSPIC33EP128GS808-E/PT
DSPIC33EP128GS708-E/PT
DSPIC33EP64GS808T-E/PT
DSPIC33EP64GS708T-I/PT
DSPIC33EP64GS808T-I/PT
DSPIC33EP128GS708T-I/PTC02
DSPIC33EP128GS708T-I/PTC01
DSPIC33EP128GS808T-I/PT
DSPIC33EP128GS708T-I/PT
DSPIC33EP64GS708-I/PT
DSPIC33EP64GS708T-E/PT
DSPIC33EP128GS808T-E/PT
DSPIC33EP128GS708T-E/PT
PIC24FJ64GA308T-I/PT
PIC24FJ128GA308T-I/PT
PIC24FJ128GA308-I/PT
PIC24FJ64GA308-I/PT
PIC24FJ128GA306-I/PTREL
PIC24FJ64GA306-I/PT
PIC24FJ64GA306-I/PTREL
PIC24FJ64GA306T-I/PT
PIC24FJ128GA306T-I/PT026
PIC24FJ128GA306T-I/PT025
PIC24FJ128GA306T-I/PT
PIC24FJ128GA306-I/PTC06
PIC24FJ128GA306-I/PT

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PIC18F85J94-I/PT

PIC18F85J94T-I/PT

PIC18F86J94-I/PT

PIC18F66J94T-I/PT

PIC18F65J94-I/PT

PIC18F67J94-I/PT

PIC18F66J94-I/PT

PIC18F67J94T-I/PT

PIC18F65J94T-I/PT

PIC24FJ128GB204T-I/PT024

PIC24FJ128GB204T-I/PT020

PIC24FJ128GB204-E/PT

PIC24FJ128GB204T-I/PT025

PIC24FJ128GB204T-I/PT023

PIC24FJ128GB204T-I/PT021

PIC24FJ128GB204-I/PT

PIC24FJ128GB204T-I/PT

PIC24FJ64GB204-I/PT

PIC24FJ128GA204-I/PT

PIC24FJ128GA204-E/PT

PIC24FJ64GA204T-I/PT

PIC24FJ64GA204-I/PT

PIC24FJ128GA204T-I/PT

PIC24FJ128GA406T-I/PT

PIC24FJ256GA406T-I/PT

PIC24FJ64GB406-I/PT

PIC24FJ128GB406-I/PT

PIC24FJ256GB406-I/PT

PIC24FJ128GB406T-I/PT

PIC24FJ256GB406T-I/PT

PIC24FJ64GA406T-I/PT

PIC24FJ64GB406T-I/PT

PIC24FJ64GA406-I/PT

PIC24FJ128GA406-I/PT

PIC24FJ256GA406-I/PT

PIC32MX274F256D-V/PT

PIC32MX154F128D-V/PT

PIC32MX174F256D-V/PT

PIC32MX174F256D-I/PT

PIC32MX254F128D-V/PT

PIC32MX254F128D-I/PT

PIC32MX274F256D-I/PT

PIC32MX154F128D-I/PT

PIC32MX274F256DT-I/PT

PIC32MX174F256DT-V/PT

PIC32MX254F128DT-I/PT

PIC32MX154F128DT-I/PT

PIC32MX174F256DT-I/PT

PIC32MX254F128DT-V/PT

PIC32MX154F128DT-V/PT

PIC32MX274F256DT-V/PT

PIC24FJ128GC006-I/PT

PIC24FJ64GC006-I/PT



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: DSNO-22KOEN225

**Date:
November 25, 2024**

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected DSPIC33EP64GS808xx, DSPIC33EP128GS808xx, DSPIC33EP128GS708xx, DSPIC33EP64GS708xx, PIC24FJ64GA308xx, PIC24FJ128GA308xx, PIC24FJ128GA306xx, PIC24FJ64GA306xx, PIC18F87J94xx, PIC18F85J94xx, PIC18F86J94xx, PIC18F66J94xx, PIC18F65J94xx, PIC18F67J94xx, PIC24FJ128GB204xx, PIC24FJ64GB204xx, PIC24FJ128GA204xx, PIC24FJ64GA204xx, PIC24FJ128GA406xx, PIC24FJ256GA406xx, PIC24FJ64GB406xx, PIC24FJ128GB406xx, PIC24FJ256GB406xx, PIC24FJ64GA406xx, PIC32MX274F256Dxx, PIC32MX154F128Dxx, PIC32MX174F256Dxx, PIC32MX254F128Dxx, PIC24FJ128GC006xx and PIC24FJ64GC006xx device families available in 44L and 64L TQFP (10x10x1mm) and 80L TQFP (12x12x1mm) packages at MTAI assembly site.

PACKAGE QUALIFICATION REPORT

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected DSPIC33EP64GS808xx, DSPIC33EP128GS808xx, DSPIC33EP128GS708xx, DSPIC33EP64GS708xx, PIC24FJ64GA308xx, PIC24FJ128GA308xx, PIC24FJ128GA306xx, PIC24FJ64GA306xx, PIC18F87J94xx, PIC18F85J94xx, PIC18F86J94xx, PIC18F66J94xx, PIC18F65J94xx, PIC18F67J94xx, PIC24FJ128GB204xx, PIC24FJ64GB204xx, PIC24FJ128GA204xx, PIC24FJ64GA204xx, PIC24FJ128GA406xx, PIC24FJ256GA406xx, PIC24FJ64GB406xx, PIC24FJ128GB406xx, PIC24FJ256GB406xx, PIC24FJ64GA406xx, PIC32MX274F256Dxx, PIC32MX154F128Dxx, PIC32MX174F256Dxx, PIC32MX254F128Dxx, PIC24FJ128GC006xx and PIC24FJ64GC006xx device families available in 44L and 64L TQFP (10x10x1mm) and 80L TQFP (12x12x1mm) packages at MTAI assembly site.

CN: E000240628
QUAL ID: R2401107 (Rev. A)
MP CODE: TLAK14V7XQEF
Part No.: DSPIC33EP512GM710-E/PT
Bonding No.: BD-002574 Rev. 01
CCB No.: 7116 and 7116.002

Lead Frame

Paddle Size: 240 x 240 mils
Material: C7025
Surface: Bare Cu
Process: Stamped
Lead Lock: No
Part Number: 10110002
Plating Composition: Matte Sn
Treatment BOT

Bond Wire

Wire: CuPdAu wire

Die Attach Material

Epoxy: QMI519

Mold Compound

Mold Compound: G700HA

Package

Type: 100L TQFP
Package Size: 12 x 12 mm

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI251901814.000	TC11925144269.210	2432U5E
MTAI252000203.000	TC11925144269.200	2433U5C
MTAI252000528.000	TC11925144269.220	2433VGD

Result: **Pass**

Conclusion:

100L TQFP (12x12 mm) assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition	Electrical Test: +25°C, 85°C, 125°C and 150°C System: J750	JESD22-A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/IPC/JEDEC J-STD-020E	693			
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH		693			
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243		693			
	Electrical Test: +25°C, 85°C, 125°C and 150°C System: J750		693(0)	0/693	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104	231(0)	0/231	Pass	Parts had been pre-conditioned at 260°C
	Electrical Test: +85°C, 125°C and 150°C System: J750			0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>3.00 grams)	Mil. Std. 883-2011	15(0)	0/15	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118	231(0)	0/231	Pass	Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: J750			0/231	Pass	77 units / lot

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: VDD=3.6 Volts System: HAST 6000X	JESD22-A110	231(0)	0/231	Pass	Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C, 125°C and 150°C System: J750			0/231	Pass	77 units / lot

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs. System: TPS Bake Oven	JESD22-A103	135(0)	0/135	Pass	45 units / lot
	Electrical Test: +25°C, 85°C, 125°C and 150°C System: J750			0/135	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Bond Strength Data Assembly	Wire Pull (>3.00 grams)	Mil. Std. 883-2011	30(0)	0/30	Pass	
	Bond Shear (>12.60 grams)	CDF-AEC-Q100 -001	30(0)	0/30	Pass	